

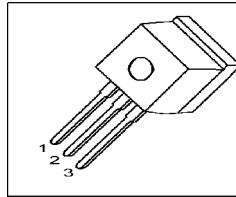
## SIPMOS® Power-Transistor Feature

- N-Channel
- Enhancement mode
- Logic Level
- 175°C operating temperature
- Avalanche rated
- dv/dt rated
- Green Package (lead free)

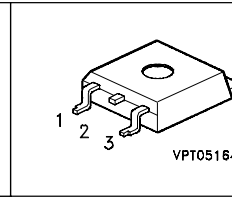
### Product Summary

$V_{DS}$	100	V
$R_{DS(on)}$	16	mΩ
$I_D$	70	A

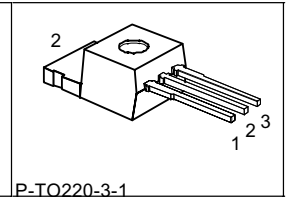
P-TO262-3-1



P-TO263-3-2

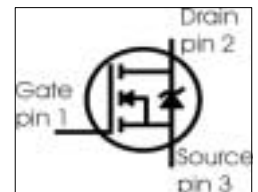


P-TO220-3-1



P-TO220-3-1

Type	Package	Ordering Code	Marking
IPP70N10SL-16	PG-TO220-3-1	SP0002-25708	N10L16
IPB70N10SL-16	PG-TO263-3-2	SP0002-25700	N10L16
IPI70N10SL-16	PG-TO262-3-1	SP000225705	N10L-16



### Maximum Ratings, at $T_j = 25\text{ °C}$ , unless otherwise specified

Parameter	Symbol	Value	Unit
Continuous drain current	$I_D$	70	A
$T_C=25\text{ °C}$		70	
$T_C=100\text{ °C}$		50	
Pulsed drain current	$I_{D\text{ puls}}$	280	
$T_C=25\text{ °C}$			
Avalanche energy, single pulse	$E_{AS}$	700	mJ
$I_D=70\text{ A}$ , $V_{DD}=25\text{ V}$ , $R_{GS}=25\text{ Ω}$			
Avalanche energy, periodic limited by $T_{i\text{max}}$	$E_{AR}$	25	
Reverse diode dv/dt	dv/dt	6	kV/μs
$I_S=70\text{ A}$ , $V_{DS}=0\text{ V}$ , $di/dt=200\text{ A/μs}$			
Gate source voltage	$V_{GS}$	±20	V
Power dissipation	$P_{\text{tot}}$	250	W
$T_C=25\text{ °C}$			
Operating and storage temperature	$T_j, T_{\text{sta}}$	-55... +175	°C
IEC climatic category; DIN IEC 68-1		55/175/56	

### Thermal Characteristics

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Characteristics</b>					
Thermal resistance, junction - case	$R_{thJC}$	-	-	0.6	K/W
Thermal resistance, junction - ambient, leaded	$R_{thJA}$	-	-	62.5	
SMD version, device on PCB: @ min. footprint @ 6 cm <sup>2</sup> cooling area <sup>1)</sup>	$R_{thJA}$	-	-	62 40	

### Electrical Characteristics, at $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Static Characteristics</b>					
Drain-source breakdown voltage $V_{GS}=0V, I_D=2mA$	$V_{(BR)DSS}$	100	-	-	V
Gate threshold voltage, $V_{GS} = V_{DS}$ $I_D = 2\text{ mA}$	$V_{GS(th)}$	1.2	1.6	2	
Zero gate voltage drain current $V_{DS}=100V, V_{GS}=0V, T_j=25^\circ\text{C}$ $V_{DS}=100V, V_{GS}=0V, T_j=150^\circ\text{C}$	$I_{DSS}$	-	0.1	1 100	$\mu\text{A}$
Gate-source leakage current $V_{GS}=20V, V_{DS}=0V$	$I_{GSS}$	-	10	100	
Drain-source on-state resistance $V_{GS}=4.5V, I_D=50A$	$R_{DS(on)}$	-	14	25	$\text{m}\Omega$
Drain-source on-state resistance $V_{GS}=10V, I_D=50A$	$R_{DS(on)}$	-	10	16	

<sup>1</sup>Device on 40mm\*40mm\*1.5mm epoxy PCB FR4 with 6cm<sup>2</sup> (one layer, 70  $\mu\text{m}$  thick) copper area for drain connection. PCB is vertical without blown air.

**Electrical Characteristics, at  $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Dynamic Characteristics**

Transconductance	$g_{fs}$	$V_{DS} \geq 2 \cdot I_D \cdot R_{DS(on)max}$ , $I_D = 50\text{A}$	30	65	-	S
Input capacitance	$C_{iss}$	$V_{GS} = 0\text{V}$ , $V_{DS} = 25\text{V}$ , $f = 1\text{MHz}$	-	3630	4540	pF
Output capacitance	$C_{oss}$		-	640	800	
Reverse transfer capacitance	$C_{rss}$		-	345	430	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 50\text{V}$ , $V_{GS} = 4.5\text{V}$ , $I_D = 70\text{A}$ , $R_G = 1.3\Omega$	-	70	105	ns
Rise time	$t_r$		-	250	375	
Turn-off delay time	$t_{d(off)}$		-	250	375	
Fall time	$t_f$		-	95	145	

**Gate Charge Characteristics**

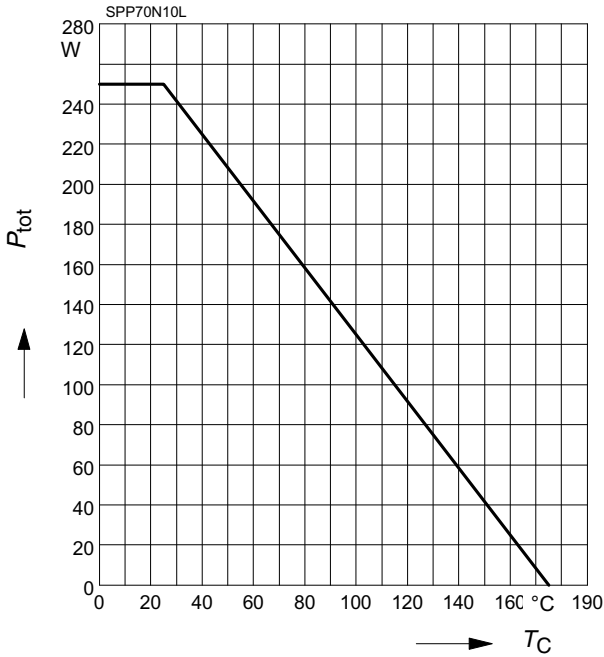
Gate to source charge	$Q_{gs}$	$V_{DD} = 80\text{V}$ , $I_D = 70\text{A}$	-	10	15	nC
Gate to drain charge	$Q_{gd}$		-	34	51	
Gate charge total	$Q_g$	$V_{DD} = 80\text{V}$ , $I_D = 70\text{A}$ , $V_{GS} = 0$ to $10\text{V}$	-	160	240	
Gate plateau voltage	$V_{(plateau)}$	$V_{DD} = 80\text{V}$ , $I_D = 70\text{A}$	-	3.22	-	V

**Reverse Diode**

Inverse diode continuous forward current	$I_S$	$T_C = 25\text{ }^\circ\text{C}$	-	-	70	A
Inv. diode direct current, pulsed	$I_{SM}$		-	-	280	
Inverse diode forward voltage	$V_{SD}$	$V_{GS} = 0\text{V}$ , $I_F = 140\text{A}$	-	1.2	1.8	V
Reverse recovery time	$t_{rr}$	$V_R = 50\text{V}$ , $I_F = I_S$ , $dI_F/dt = 100\text{A}/\mu\text{s}$	-	100	150	ns
Reverse recovery charge	$Q_{rr}$		-	600	900	nC

### 1 Power dissipation

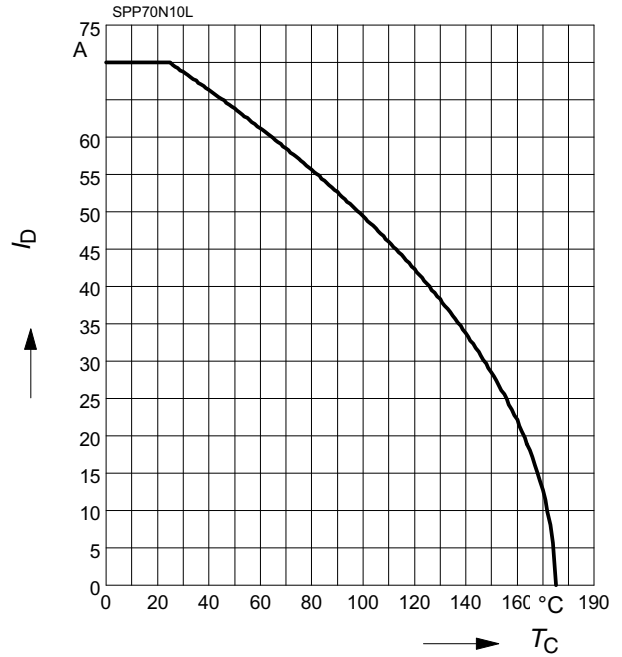
$$P_{tot} = f(T_C)$$



### 2 Drain current

$$I_D = f(T_C)$$

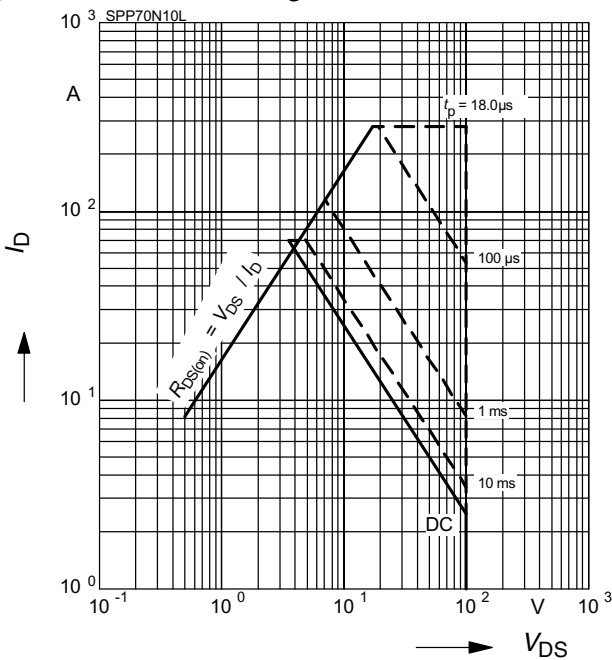
parameter:  $V_{GS} \geq 10 \text{ V}$



### 3 Safe operating area

$$I_D = f(V_{DS})$$

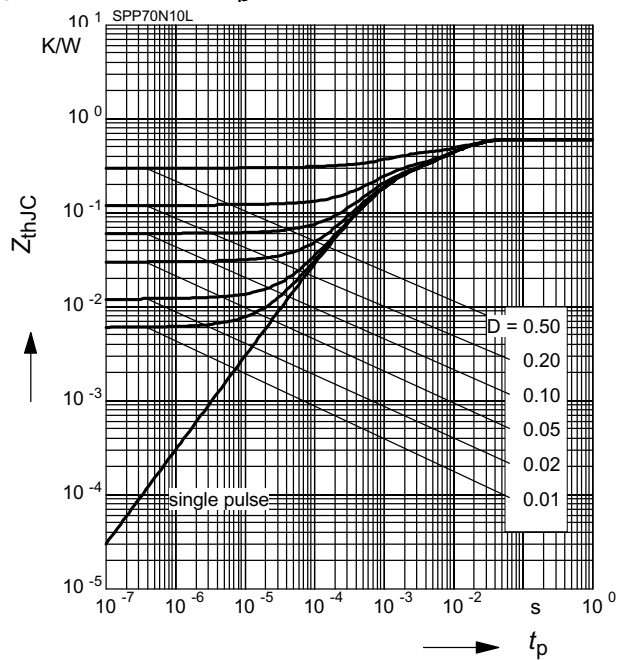
parameter :  $D = 0$  ,  $T_C = 25 \text{ }^\circ\text{C}$



### 4 Max. transient thermal impedance

$$Z_{thJC} = f(t_p)$$

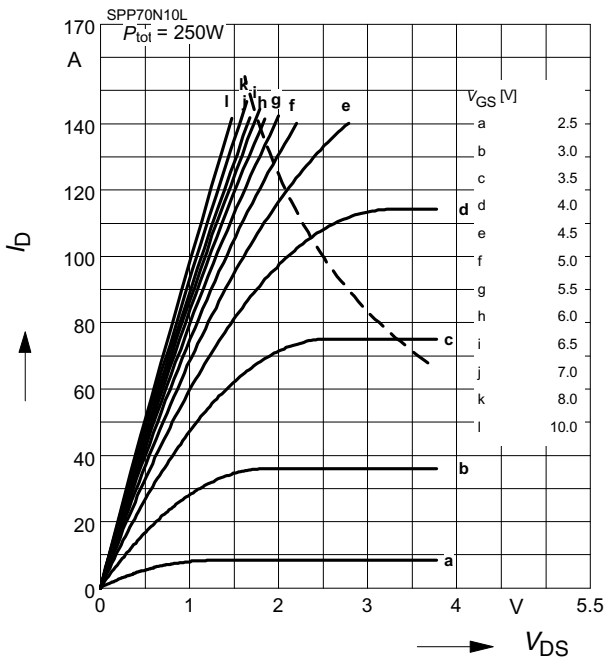
parameter :  $D = t_p/T$



**5 Typ. output characteristic**

$I_D = f(V_{DS}); T_j = 25^\circ\text{C}$

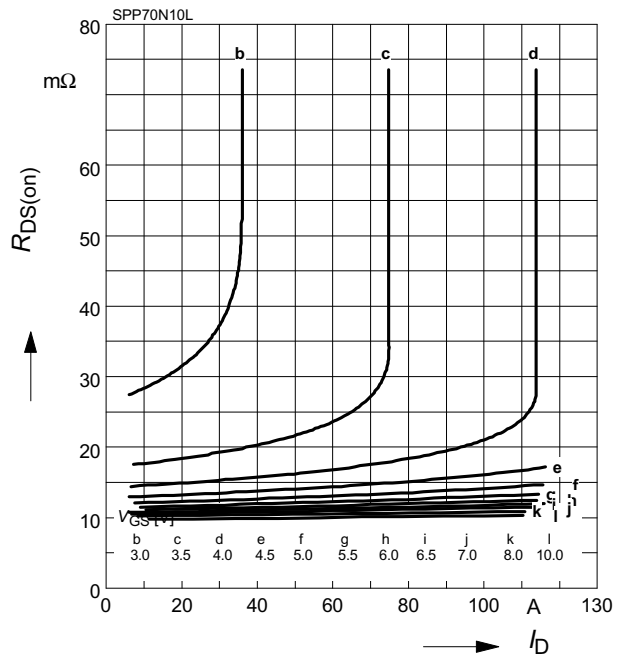
parameter:  $t_b = 80 \mu\text{s}$



**6 Typ. drain-source on resistance**

$R_{DS(on)} = f(I_D)$

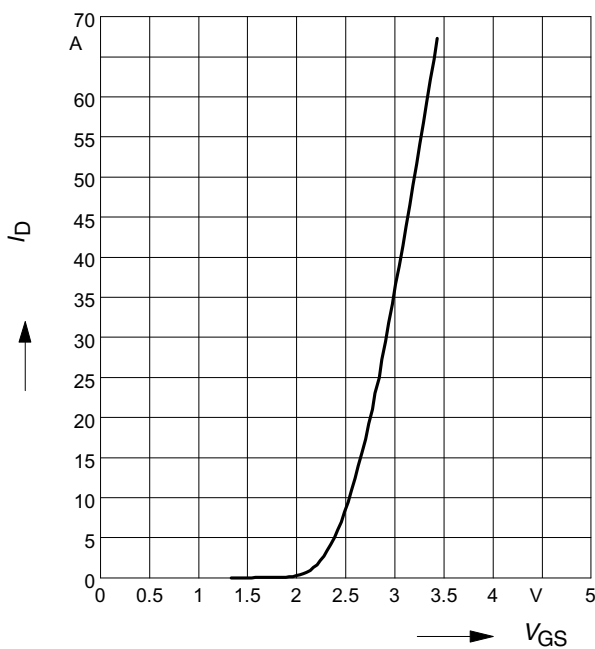
parameter:  $V_{GS}$



**7 Typ. transfer characteristics**

$I_D = f(V_{GS}); V_{DS} \geq 2 \times I_D \times R_{DS(on)max}$

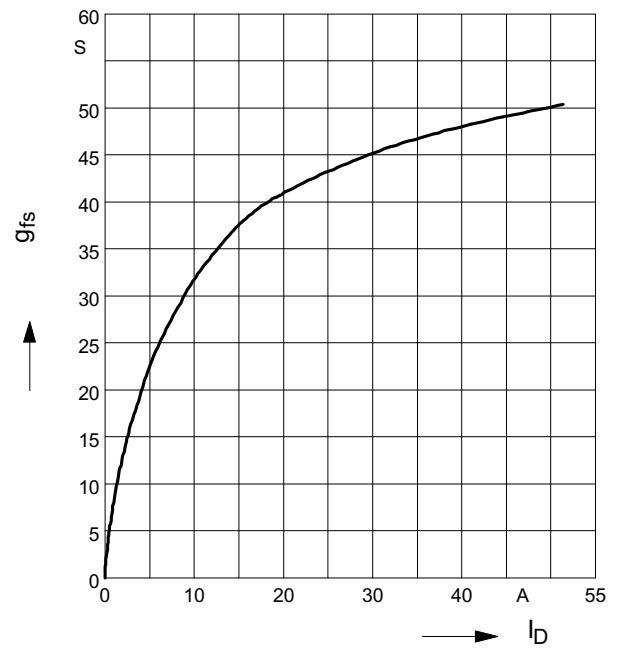
parameter:  $t_b = 80 \mu\text{s}$



**8 Typ. forward transconductance**

$g_{fs} = f(I_D); T_j = 25^\circ\text{C}$

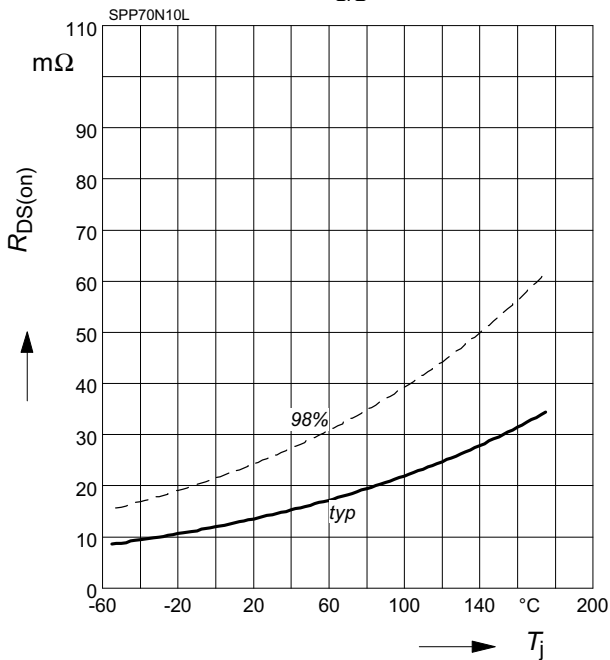
parameter:  $g_{fs}$



### 9 Drain-source on-state resistance

$$R_{DS(on)} = f(T_j)$$

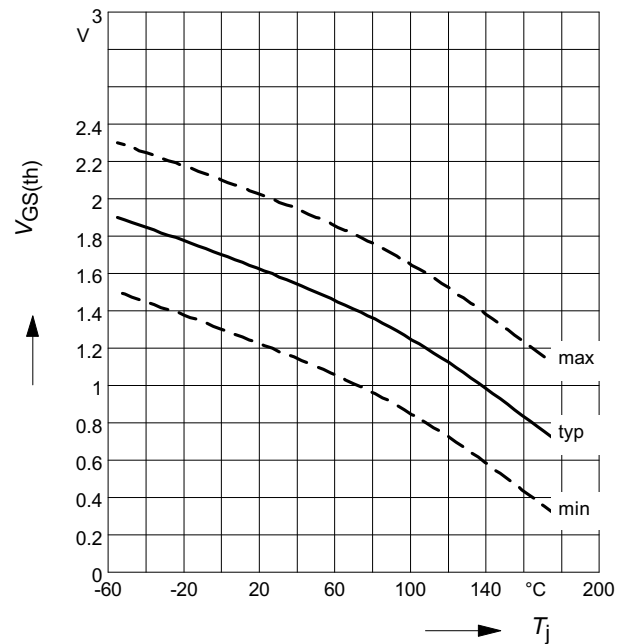
parameter:  $I_D = 50\text{ A}$ ,  $V_{GS} = 4.5\text{ V}$



### 10 Typ. gate threshold voltage

$$V_{GS(th)} = f(T_j)$$

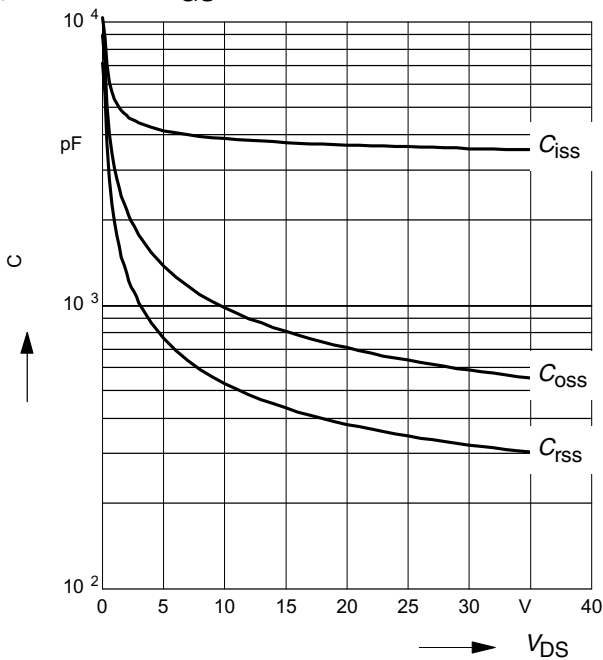
parameter:  $V_{GS} = V_{DS}$ ,  $I_D = 2\text{ mA}$



### 11 Typ. capacitances

$$C = f(V_{DS})$$

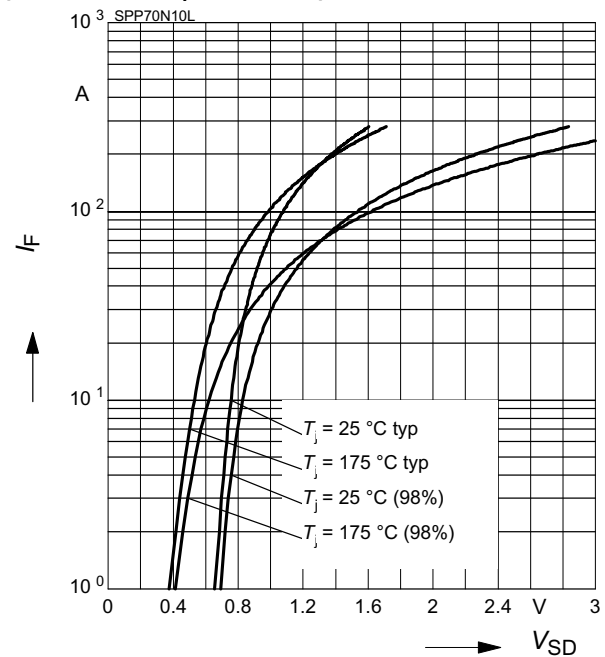
parameter:  $V_{GS} = 0\text{ V}$ ,  $f = 1\text{ MHz}$



### 12 Forward character. of reverse diode

$$I_F = f(V_{SD})$$

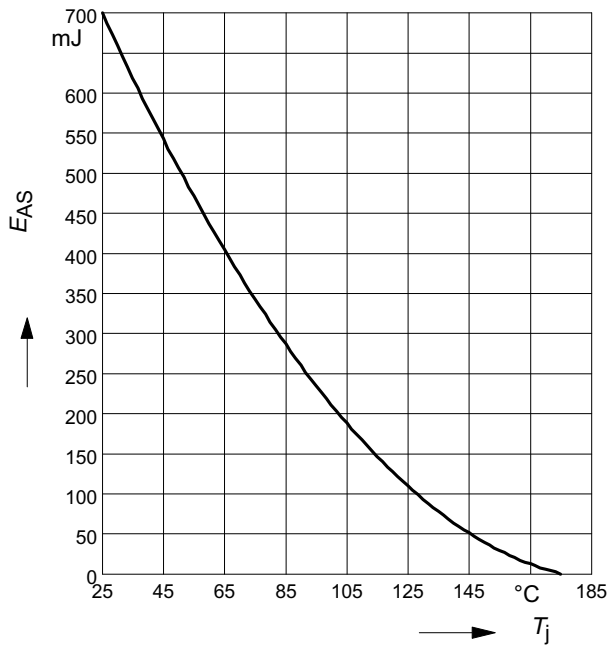
parameter:  $T_j$ ,  $t_p = 80\text{ }\mu\text{s}$



### 13 Typ. avalanche energy

$$E_{AS} = f(T_j)$$

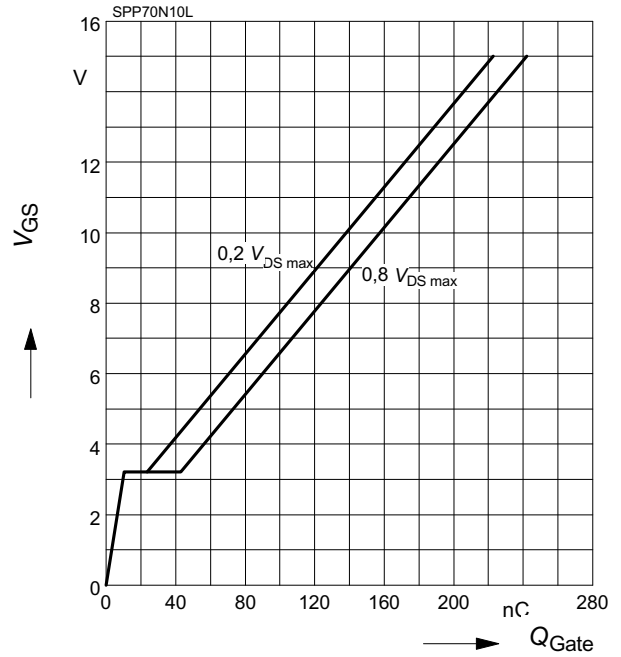
par.:  $I_D = 70\text{ A}$  ,  $V_{DD} = 25\text{ V}$  ,  $R_{GS} = 25\ \Omega$



### 14 Typ. gate charge

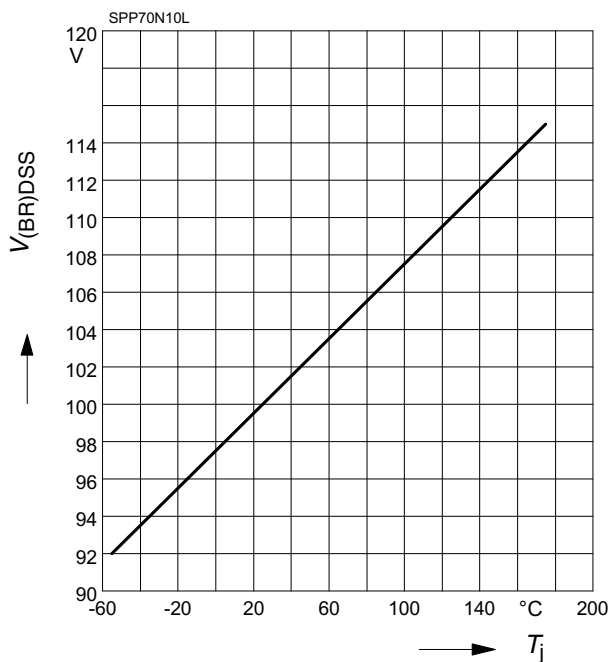
$$V_{GS} = f(Q_{Gate})$$

parameter:  $I_D = 70\text{ A}$  pulsed



### 15 Drain-source breakdown voltage

$$V_{(BR)DSS} = f(T_j)$$





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